Surface Mount Schottky Barrier Rectifiers

1 A, 20 V - 150 V

SS12FP - S115FP

Features

- Larger Cathode Pad for Improved Power Dissipation
- Ultra Thin Profile Package Height < 1.0 mm
- High Surge Current Capability
- Low Power Loss, High Efficiency
- UL Flammability 94V-0 Classification
- MSL 1 per J-STD-020
- AEC-Q101 Qualified
- These Devices are Pb-Free and are RoHS Compliant

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

		Value						
Symbol	Parameter	SS12 FP	SS13 FP	SS14 FP	SS16 FP	S110 FP	S115 FP	Unit
V _{RRM}	Repetitive Peak Reverse Voltage	20	30	40	60	100	150	٧
V _{RMS}	RMS Reverse Voltage	14	21	28	42	70	105	٧
V _R	DC Blocking Voltage	20	30	40	60	100	150	٧
I _{F(AV)}	Average Forward Rectified Current		1					Α
I _{FSM}	Peak Forward Surge Current: 8.3 ms Single Half Sine-Wave Superimposed on Rated Load		30					A
TJ	Operating Junction Temperature Range	-55 to +125 -55 to +150			°C			
T _{STG}	Storage Temperature Range	-55 to +150				°C		

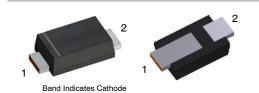
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

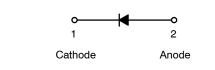


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SOD-123EP CASE 425AC



MARKING DIAGRAM



&Y = Binary Calendar Year Coding &Z = Assembly Plant Code XFP = Specific Device Code X = 0, 2, 3, 4, 6, A &G = Single Digit Week Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

SS12FP - S115FP

THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Note 1)

Symbol	Parameter	Value	Unit
$\Psi_{\sf JL}$	Thermal Characteristics, Junction-to-Lead (Note 2)	10	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	140	°C/W

^{1.} Per JESD51-3 recommended thermal test board. Device mounted on FR-4 PCB, board size = 76.2 mm x 114.3 mm.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

		Value							
Symbol	Parameter	Conditions	SS12 FP	SS13 FP	SS14 FP	SS16 FP	S110 FP	S115 FP	Unit
V _F	Forward Voltage (Note 3)	I _F = 0.5 A			0.51	0.58	0.70	0.75	V
ĮF		I _F = 1.0 A	0.45	0.50	0.55	0.70	0.80	0.90	1
I _R Maximum Reverse Current	T _J = 25°C	0.40			0.05		mA		
at Rated V _R		T _J = 125°C				0.50			
CJ	Typical Junction Capacitance	V _R = 4 V, f = 1 MHz	54		2	8	pF		
Trr		I _F = 0.5 A, I _R = 1 A, I _{RR} = 0.25 A	6		14		ns		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Device Code Marking	Package	Packing Method [†]
SS12FP	2FP	SOD-123EP	Tape and Reel
SS13FP	3FP	SOD-123EP	Tape and Reel
SS14FP	4FP	SOD-123EP	Tape and Reel
SS16FP	6FP	SOD-123EP	Tape and Reel
S110FP	0FP	SOD-123EP	Tape and Reel
S115FP	AFP	SOD-123EP	Tape and Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{2.} Thermocouple soldered at cathode lead.

^{3.} Pulse test with PW = 300 μ s, 1% duty cycle.

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TYPICAL PERFORMANCE CHARACTERISTICS

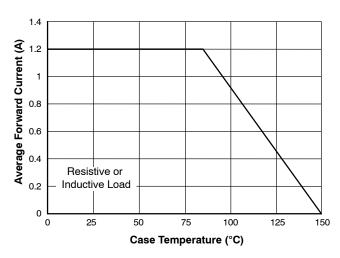


Figure 1. Forward Current Derating Curve

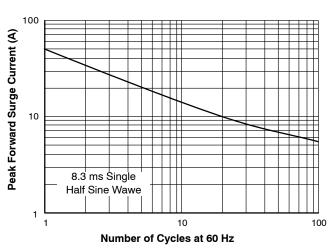


Figure 2. Maximum Non-Repetitive Forward Surge Current

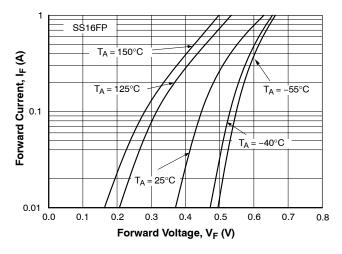


Figure 3. Typical Forward Characteristics

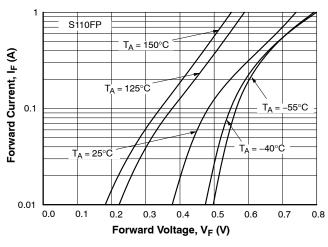


Figure 4. Typical Forward Characteristics

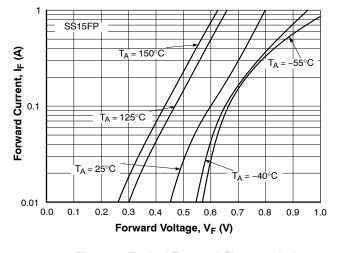


Figure 5. Typical Forward Characteristic

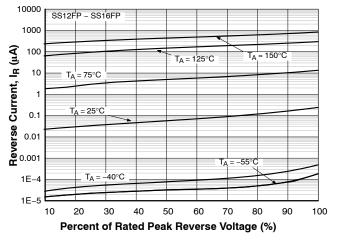


Figure 6. Typical Reverse Characteristics

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TYPICAL PERFORMANCE CHARACTERISTICS

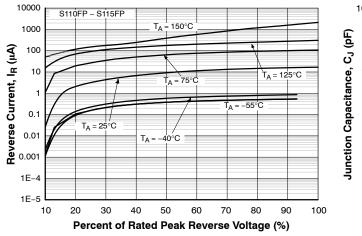


Figure 7. Typical Reverse Characteristic

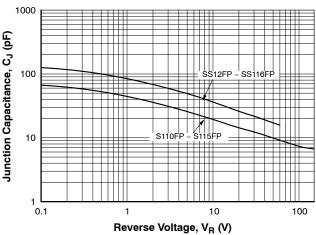
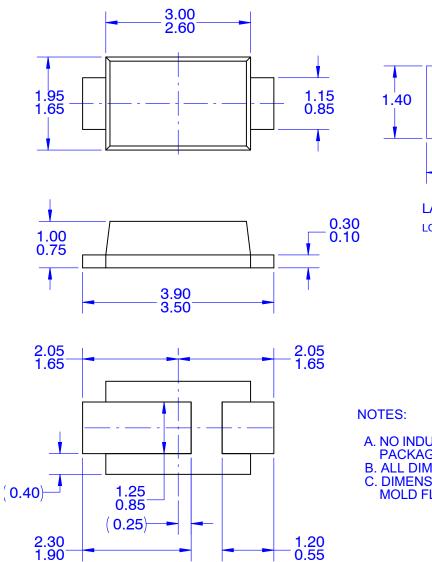
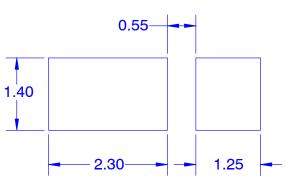


Figure 8. Typical Junction Capacitance

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DATE 31 AUG 2016





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